

Revolutionizing Semiconductor Wafer Testing: A Breakthrough in Ultra-Precise High-Performance Foil Material



Thilo Happ - E-Mail: t.happ@sickert-hafner.de

Vision

With over a decade of experience in precision foil engineering, we deliver a breakthrough in ultra-precision rolling. Our advanced process enables ultra-thin foils — even from your hard-to-roll materials.

With special alloys and cutting-edge technology, we set new standards in accuracy, reproducibility, and material versatility making it ideal for probing materials.

Key features of „S-One“ alloy

Exceptional and customizable mechanical properties:

- **800 -1400 MPa** tensile strength
- up to 400 HV hardness
- ~ 120 GPa young's modulus

Outstanding **electrical** properties:

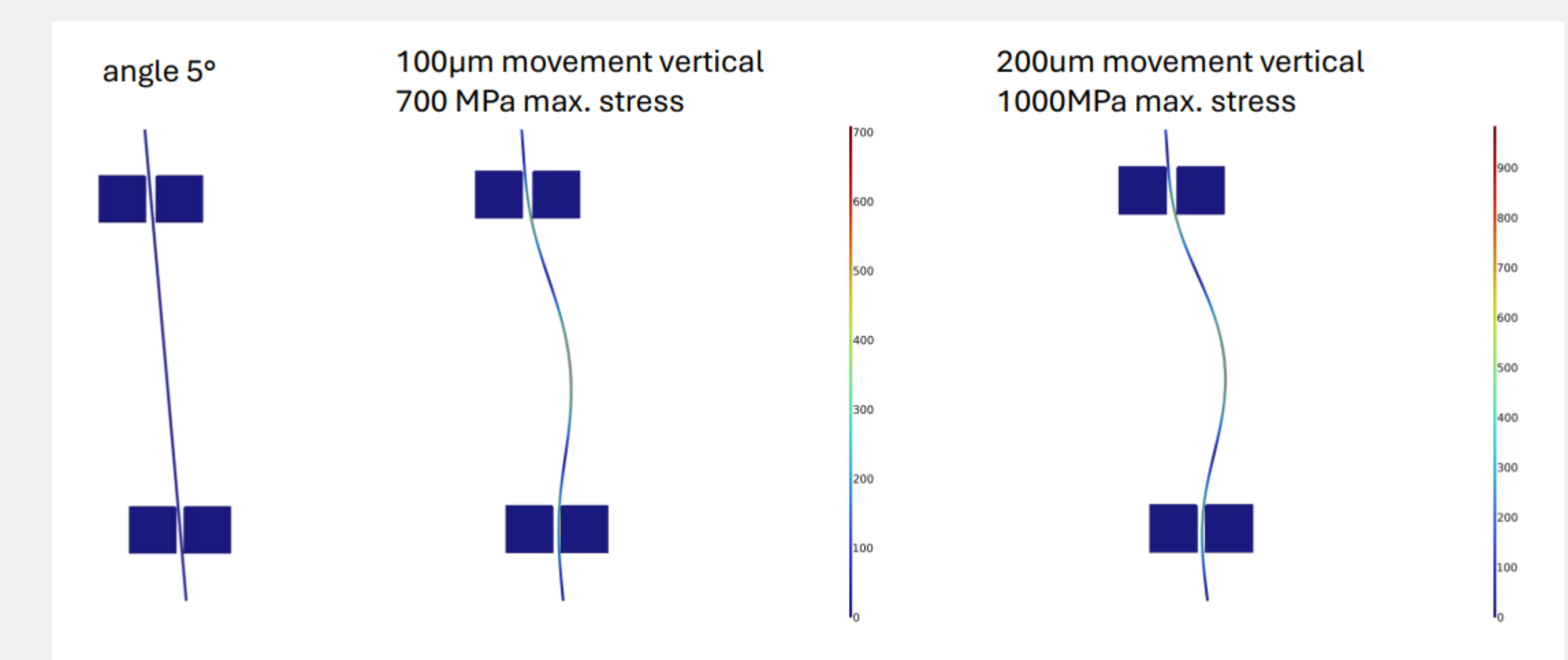
- Up to **75 % IACS** – reliable electrical performance
- Stable contact resistance – ideal for wafer level testing

Key features of „S-Tec“ precision rolling

- rolling process for ultra-precise, high-performance metal foils
- **100mm** standard **width**, custom dimensions possible
- 20–100µm thickness
- ±1µm tolerance
- Designed for next-gen semiconductor-testing foils
- Ideal **flatness** & surface quality due to „S-Tec“
- High consistency and repeatability

Materials design assisted by numerical simulation of final application

Our processes are tailored to the needs of probing material applications. We can design the optimal alloy properties for the real application in the final system by numerical simulation of thermal and mechanical stresses.



Conclusion

- Combining start-up agility with deep process know-how
- Customer-focused and agile development
- Rolling your material with ultra-precision
- Simulation of thermal and mechanical stresses in the needle
- Development of proprietary alloys with high strength and high electrical conductivity